

# Infineon Wi-Fi firmware – CYW5557x (v2025\_0718) release notes

## **About this document**

#### **Scope and purpose**

This document provides an overview of the bug fixes and known issues in the firmware for the AIROC™ CYW5557x Wi-Fi + Bluetooth® Combo chip, as part of the Infineon Wi-Fi firmware release – CYW5557x (v2025\_0718) for the Linux ecosystem.

#### **Intended audience**

This document is intended for users configuring the AIROC™ Wi-Fi – Bluetooth® Combo device over a Linux-based environment.

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#### **Overview**

# 1 Overview

## 1.1 Brief summary

This document is intended to provide information on the bug fixes and known issues in the firmware for AIROC™ CYW5557x Wi-Fi + Bluetooth® Combo chip in the Infineon Wi-Fi firmware release – CYW5557x (v2025\_0718).

This release includes the following:

- Firmware and CLM blob
  - ifx-Linux-firmware GitHub page

#### 1.2 Device firmware revision details

Table 1 Firmware revision details

Device		Wi-Fi firmware version
CYW55571	PCle	18.53.469.33
CYW55572	SDIO	
CYW55573		

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#### Firmware updates

# **2** Firmware updates

## 2.1 CYW55571/CYW55572/CYW55573

#### **Bug fixes**

- Fix for driver and wl command issues observed at 85°C temperature
- Fix for ping failures and iperf failures during throughput testing
- Fix for NSS stream selection error observed during RvR performance and throughput testing

#### **Known issues**

[SDIO] [Intermittent] Notice low Rx throughput during WLAN and ACL traffic co-ex scenarios.

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